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## Product Change Notification - KSRA-02RRCB401 (Printer Friendly)

### Date:

05 Jun 2017

### Product Category:

Linear Op Amps; Interface- Passive-Keyless-Entry Analog Front End; Touch Controllers; Interface- Infrared Products; Interface- Controller Area Network (CAN); Successive Approximation Register (SAR) A/D Converters; Digital Potentiometers; Linear Comparators; Linear Selectable Gain Amplifiers; Linear Programmable Gain Amplifiers; 8-bit PIC Microcontrollers

### Notification subject:

CCB 2852: Final Notice: Qualification of CuPdAu bond wire for selected products of 120K wafer technology available in 14L SOIC package at MMT assembly site using 95x155 mils lead frame paddle size

### Notification text:

#### PCN Status:

Final notification

### Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 120K wafer technology available in 14L SOIC package at MMT assembly site using 95x155 mils lead frame paddle size

### Pre Change:

Assembled at MMT using gold (Au) bond wire, 90X110 mils lead frame paddle size, spot LF plating and assembled in MTAI using Palladium coated copper (PdCu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

### Post Change:

Assembled in MMT using palladium coated copper with gold flash (CuPdAu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

### Pre and Post Change Summary:

	Pre Change		Post Change
<b>Assembly Site</b>	MMT	MTAI	MMT
<b>Wire material</b>	Au Wire	PdCu Wire	CuPdAu Wire
<b>Die attach material</b>	8390A	8390A	8390A
<b>Molding compound material</b>	G600V	G600V	G600V
<b>Lead frame material</b>	C194	C194	C194
<b>Lead Frame Paddle Size</b>	90x110 mils	95x155 mils	95x155 mils
<b>LF Surface</b>	Spot	Bare Cu	Bare Cu

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

June 12, 2017 (date code: 1724)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	February 2017					-->	May 2017					June 2017			
	05	06	07	08	09		18	19	20	21	22	23	24	25	26
Workweek															
Initial PCN Issue Date			X												
Qual Report Availability							X								
Final PCN Issue Date							X								



